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## PATENT ABSTRACTS OF JAPAN

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**(54) DEVICE AND METHOD FOR PLATING****(57) Abstract:**

**PURPOSE:** To obtain a plating film precisely uniform in film quality, composition and film thickness on a wafer by controlling the change in characteristics such as conc. of a plating solution which flows along a cathode electrode in plating using a rotary cathode electrode.

**CONSTITUTION:** The disk type rotary electrode 3 rotating to circumferential direction, on one side of which a sample is fitted, and the anodic electrode 4, 4... provided against the described one side are arranged in a plating solution, and electroplating is executed by energizing between these electrodes. The inner vessel 12, inside of which the plural cylindrical inner wall 121, 121... is provided, is provided on axial line of the rotary shaft 30 of the rotary electrode 3 and the plating solution is supplied from the columnary space 122 in the inner

vessel 12 and cylindrical space 123, 123... respectively to the rotary electrode 3. And the supplying amount of the plating solution supplied from each of the columnary space 122 and the cylindrical space 123, 123... is regulated to increase from the inside towards the outside of the inner vessel 12.

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